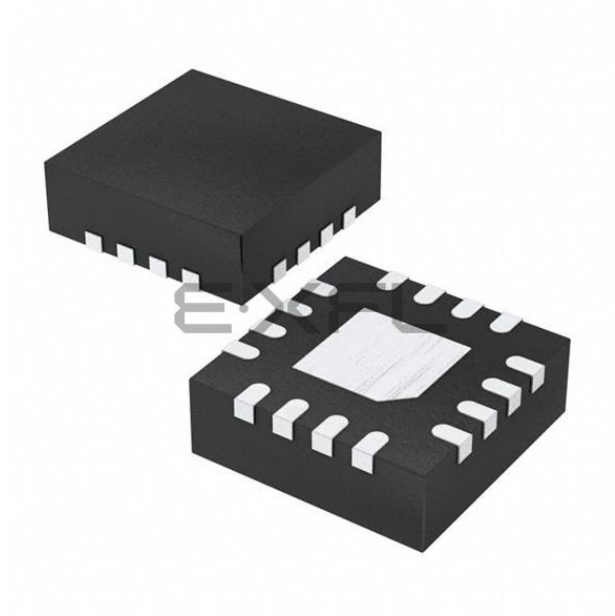

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Applications of "Embedded - Microcontrollers"

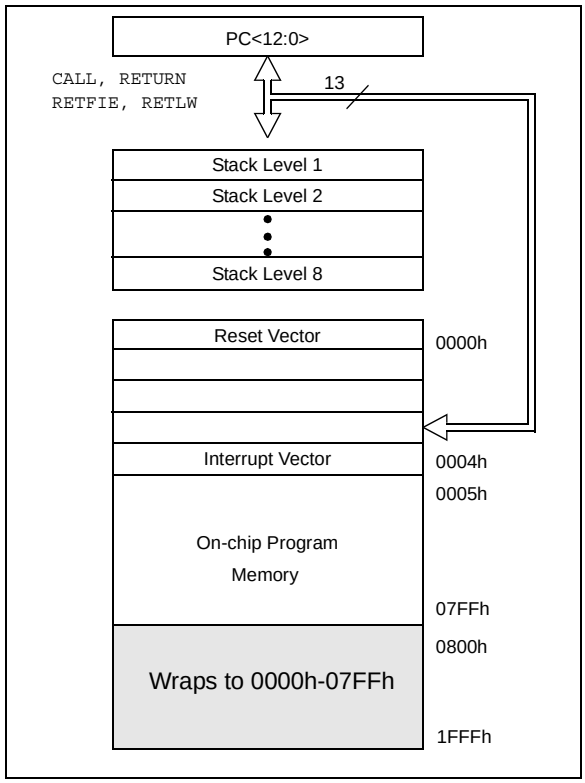
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VQFN Exposed Pad
Supplier Device Package	16-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f684t-i-ml

2.0 MEMORY ORGANIZATION

2.1 Program Memory Organization

The PIC16F684 has a 13-bit program counter capable of addressing an 8k x 14 program memory space. Only the first 2k x 14 (0000h-07FFh) for the PIC16F684 is physically implemented. Accessing a location above these boundaries will cause a wrap around within the first 2k x 14 space. The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figure 2-1).

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16F684



2.2 Data Memory Organization

The data memory (see Figure 2-2) is partitioned into two banks, which contain the General Purpose Registers (GPR) and the Special Function Registers (SFR). The Special Function Registers are located in the first 32 locations of each bank. Register locations 20h-7Fh in Bank 0 and A0h-BFh in Bank 1 are General Purpose Registers, implemented as static RAM. Register locations F0h-FFh in Bank 1 point to addresses 70h-7Fh in Bank 0. All other RAM is unimplemented and returns '0' when read. The RP0 bit of the STATUS register is the bank select bit.

RP0

0 → Bank 0 is selected

1 → Bank 1 is selected

Note:	The IRP and RP1 bits of the STATUS register are reserved and should always be maintained as '0's.

REGISTER 8-1: CMCON0: COMPARATOR CONFIGURATION REGISTER

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **C2OUT:** Comparator 2 Output bit
When C2INV = 0:
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-
When C2INV = 1:
1 = C2 VIN+ < C2 VIN-
0 = C2 VIN+ > C2 VIN-

bit 6 **C1OUT:** Comparator 1 Output bit
When C1INV = 0:
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-
When C1INV = 1:
1 = C1 VIN+ < C1 VIN-
0 = C1 VIN+ > C1 VIN-

bit 5 **C2INV:** Comparator 2 Output Inversion bit
1 = C2 output inverted
0 = C2 output not inverted

bit 4 **C1INV:** Comparator 1 Output Inversion bit
1 = C1 Output inverted
0 = C1 Output not inverted

bit 3 **CIS:** Comparator Input Switch bit
When CM<2:0> = 010:
1 = C1IN+ connects to C1 VIN-
C2IN+ connects to C2 VIN-
0 = C1IN- connects to C1 VIN-
C2IN- connects to C2 VIN-
When CM<2:0> = 001:
1 = C1IN+ connects to C1 VIN-
0 = C1IN- connects to C1 VIN-

bit 2-0 **CM<2:0>:** Comparator Mode bits (See Figure 8-5)
000 = Comparators off. CxIN pins are configured as analog
001 = Three inputs multiplexed to two comparators
010 = Four inputs multiplexed to two comparators
011 = Two common reference comparators
100 = Two independent comparators
101 = One independent comparator
110 = Two common reference comparators with outputs
111 = Comparators off. CxIN pins are configured as digital I/O

9.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Results formatting

9.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. See the corresponding port section for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

9.1.2 CHANNEL SELECTION

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 9.2 "ADC Operation"** for more information.

9.1.3 ADC VOLTAGE REFERENCE

The VCFG bit of the ADCON0 register provides control of the positive voltage reference. The positive voltage reference can be either VDD or an external voltage source. The negative voltage reference is always connected to the ground reference.

9.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 10-bit conversion requires 11 TAD periods as shown in Figure 9-3.

For correct conversion, the appropriate TAD specification must be met. See A/D conversion requirements in **Section 15.0 "Electrical Specifications"** for more information. Table 9-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

TABLE 9-1: ADC CLOCK PERIOD (TAD) VS. DEVICE OPERATING FREQUENCIES (VDD ≥ 3.0V)

ADC Clock Period (TAD)		Device Frequency (FOSC)			
ADC Clock Source	**ADCS<2:0>**	**20 MHz**	**8 MHz**	**4 MHz**	**1 MHz**
FOSC/2	000	100 ns(2)	250 ns(2)	500 ns(2)	2.0 µs
FOSC/4	100	200 ns(2)	500 ns(2)	1.0 µs(2)	4.0 µs
FOSC/8	001	400 ns(2)	1.0 µs(2)	2.0 µs	8.0 µs(3)
FOSC/16	101	800 ns(2)	2.0 µs	4.0 µs	16.0 µs(3)
FOSC/32	010	1.6 µs	4.0 µs	8.0 µs(3)	32.0 µs(3)
FOSC/64	110	3.2 µs	8.0 µs(3)	16.0 µs(3)	64.0 µs(3)
FRC	x11	2-6 µs(1,4)	2-6 µs(1,4)	2-6 µs(1,4)	2-6 µs(1,4)

Legend: Shaded cells are outside of recommended range.

Note 1: The FRC source has a typical TAD time of 4 µs for VDD > 3.0V.

2: These values violate the minimum required TAD time.

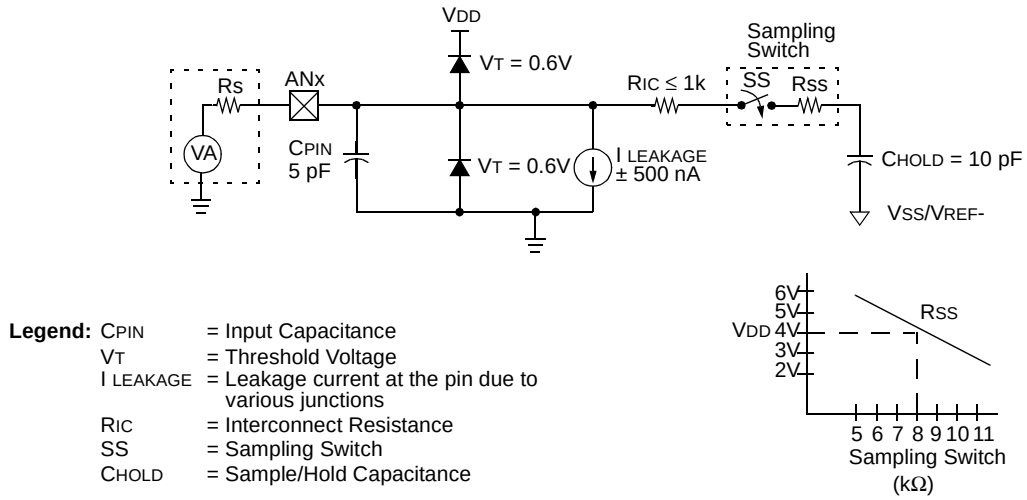
3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the FRC clock source is only recommended if the conversion will be performed during Sleep.

EXAMPLE 9-1: A/D CONVERSION

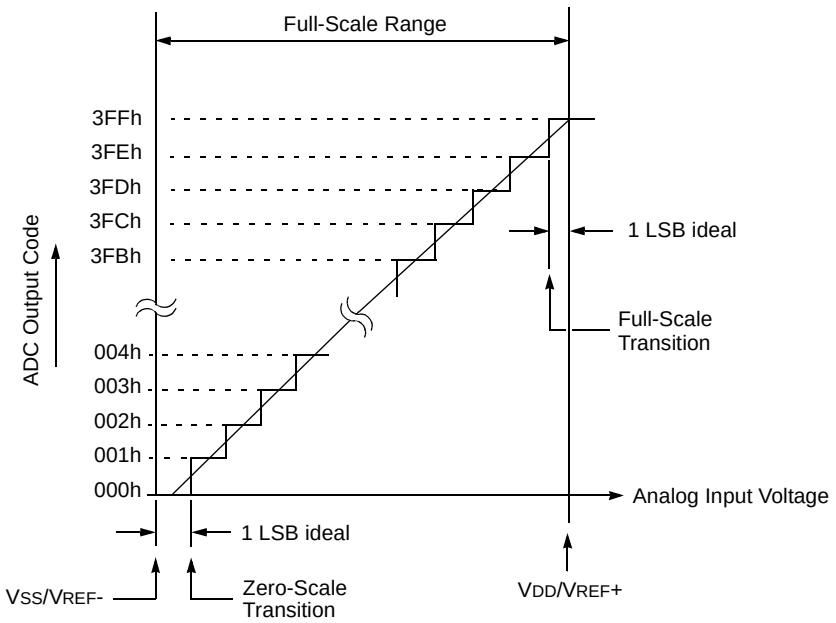
```
;This code block configures the ADC
;for polling, Vdd reference, Frc clock
;and AN0 input.
;
;Conversion start & polling for completion
; are included.
;
BANKSEL   ADCON1       ;
MOVLW     B'01110000'  ;ADC Frc clock
MOVWF     ADCON1       ;
BANKSEL   TRISA        ;
BSF       TRISA,0      ;Set RA0 to input
BANKSEL   ANSEL        ;
BSF       ANSEL,0      ;Set RA0 to analog
BANKSEL   ADCON0       ;
MOVLW     B'10000001'  ;Right justify,
MOVWF     ADCON0       ; Vdd Vref, AN0, On
CALL      SampleTime   ;Acquisiton delay
BSF       ADCON0,GO    ;Start conversion
BTFSC     ADCON0,GO    ;Is conversion done?
GOTO      $-1          ;No, test again
BANKSEL   ADRESH       ;
MOVF      ADRESH,W     ;Read upper 2 bits
MOVWF     RESULTHI     ;store in GPR space
BANKSEL   ADRESL       ;
MOVF      ADRESL,W     ;Read lower 8 bits
MOVWF     RESULTLO     ;Store in GPR space
```

FIGURE 9-4: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
VT = Threshold Voltage
I LEAKAGE = Leakage current at the pin due to various junctions
RIC = Interconnect Resistance
SS = Sampling Switch
CHOLD = Sample/Hold Capacitance

FIGURE 9-5: ADC TRANSFER FUNCTION



10.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full V_{DD} range). This memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory:

- EECON1
- EECON2 (not a physically implemented register)
- EEDAT
- EEADR

EEDAT holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC16F684 has 256 bytes of data EEPROM with an address range from 0h to FFh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature as well as from chip-to-chip. Please refer to AC Specifications in **Section 15.0 "Electrical Specifications"** for exact limits.

When the data memory is code-protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access the data EEPROM data and will read zeroes.

REGISTER 10-1: EEDAT: EEPROM DATA REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EEDAT7	EEDAT6	EEDAT5	EEDAT4	EEDAT3	EEDAT2	EEDAT1	EEDAT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **EEDATn**: Byte Value to Write To or Read From Data EEPROM bits

REGISTER 10-2: EEADR: EEPROM ADDRESS REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EEADR7	EEADR6	EEADR5	EEADR4	EEADR3	EEADR2	EEADR1	EEADR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **EEADR**: Specifies One of 256 Locations for EEPROM Read/Write Operation bits

10.2 Reading the EEPROM Data Memory

To read a data memory location, the user must write the address to the EEADR register and then set control bit RD of the EECON1 register, as shown in Example 10-1. The data is available, at the very next cycle, in the EEDAT register. Therefore, it can be read in the next instruction. EEDAT holds this value until another read, or until it is written to by the user (during a write operation).

EXAMPLE 10-1: DATA EEPROM READ

```
    BANKSEL     EEADR       ;
    MOVLW       CONFIG_ADDR ;
    MOVWF       EEADR       ;Address to read
    BSF         EECON1,RD   ;EE Read
    MOVF        EEDAT,W     ;Move data to W
```

10.3 Writing to the EEPROM Data Memory

To write an EEPROM data location, the user must first write the address to the EEADR register and the data to the EEDAT register. Then the user must follow a specific sequence to initiate the write for each byte, as shown in Example 10-2.

EXAMPLE 10-2: DATA EEPROM WRITE

```
    BANKSEL  EECON1       ;
    BSF      EECON1,WREN  ;Enable write
    BCF      INTCON,GIE   ;Disable INTs
    BTFSC    INTCON,GIE   ;See AN576
    GOTO     $-2          ;
    MOVLW    55h          ;Unlock write
    MOVWF    EECON2       ;
    MOVLW    AAh          ;
    MOVWF    EECON2       ;
    BSF      EECON1,WR    ;Start the write
    BSF      INTCON,GIE   ;Enable INTS
```

Required Sequence

The write will not initiate if the above sequence is not exactly followed (write 55h to EECON2, write AAh to EECON2, then set WR bit) for each byte. We strongly recommend that interrupts be disabled during this code segment. A cycle count is executed during the required sequence. Any number that is not equal to the required cycles to execute the required sequence will prevent the data from being written into the EEPROM.

Additionally, the WREN bit in EECON1 must be set to enable write. This mechanism prevents accidental writes to data EEPROM due to errant (unexpected) code execution (i.e., lost programs). The user should keep the WREN bit clear at all times, except when updating EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, clearing the WREN bit will not affect this write cycle. The WR bit will be inhibited from being set unless the WREN bit is set.

At the completion of the write cycle, the WR bit is cleared in hardware and the EE Write Complete Interrupt Flag bit (EEIF) is set. The user can either enable this interrupt or poll this bit. The EEIF bit of the PIR1 register must be cleared by software.

10.4 Write Verify

Depending on the application, good programming practice may dictate that the value written to the data EEPROM should be verified (see Example 10-3) to the desired value to be written.

EXAMPLE 10-3: WRITE VERIFY

```
    BANKSELEEDAT        ;
    MOVF    EEDAT,W     ;EEDAT not changed
                        ;from previous write
    BSF     EECON1,RD   ;YES, Read the
                        ;value written
    XORWF   EEDAT,W
    BTFSS   STATUS,Z    ;Is data the same
    GOTO    WRITE_ERR   ;No, handle error
    :                   ;Yes, continue
```

10.4.1 USING THE DATA EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing information (e.g., program variables or other data that are updated often). When variables in one section change frequently, while variables in another section do not change, it is possible to exceed the total number of write cycles to the EEPROM (specification D124) without exceeding the total number of write cycles to a single byte (specifications D120 and D120A). If this is the case, then a refresh of the array must be performed. For this reason, variables that change infrequently (such as constants, IDs, calibration, etc.) should be stored in Flash program memory.

11.4 PWM (Enhanced Mode)

The Enhanced PWM Mode can generate a PWM signal on up to four different output pins with up to 10-bits of resolution. It can do this through four different PWM output modes:

- Single PWM
- Half-Bridge PWM
- Full-Bridge PWM, Forward mode
- Full-Bridge PWM, Reverse mode

To select an Enhanced PWM mode, the P1M bits of the CCP1CON register must be set appropriately.

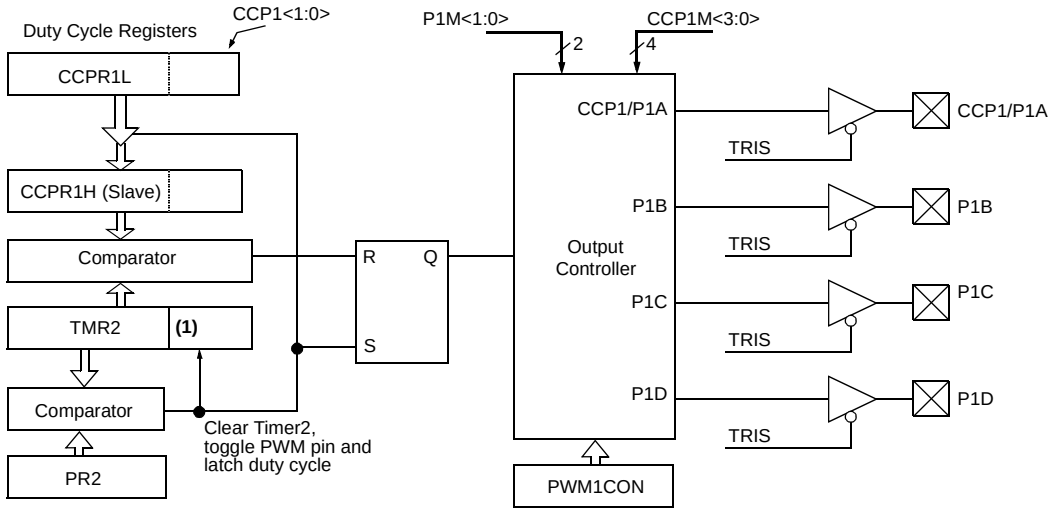
The PWM outputs are multiplexed with I/O pins and are designated P1A, P1B, P1C and P1D. The polarity of the PWM pins is configurable and is selected by setting the CCP1M bits in the CCP1CON register appropriately.

Table 11-4 shows the pin assignments for each Enhanced PWM mode.

Figure 11-5 shows an example of a simplified block diagram of the Enhanced PWM module.

Note:	To prevent the generation of an incomplete waveform when the PWM is first enabled, the ECCP module waits until the start of a new PWM period before generating a PWM signal.

FIGURE 11-5: EXAMPLE SIMPLIFIED BLOCK DIAGRAM OF THE ENHANCED PWM MODE



Note 1: The 8-bit timer TMR2 register is concatenated with the 2-bit internal Q clock, or 2 bits of the prescaler to create the 10-bit time base.

Note 1:	The TRIS register value for each PWM output must be configured appropriately.
2:	Clearing the CCP1CON register will relinquish ECCP control of all PWM output pins.
3:	Any pin not used by an Enhanced PWM mode is available for alternate pin functions

TABLE 11-4: EXAMPLE PIN ASSIGNMENTS FOR VARIOUS PWM ENHANCED MODES

ECCP Mode	P1M	CCP1/P1A	P1B	P1C	P1D
Single	00	Yes	No	No	No
Half-Bridge	10	Yes	Yes	No	No
Full-Bridge, Forward	01	Yes	Yes	Yes	Yes
Full-Bridge, Reverse	11	Yes	Yes	Yes	Yes

11.4.2 FULL-BRIDGE MODE

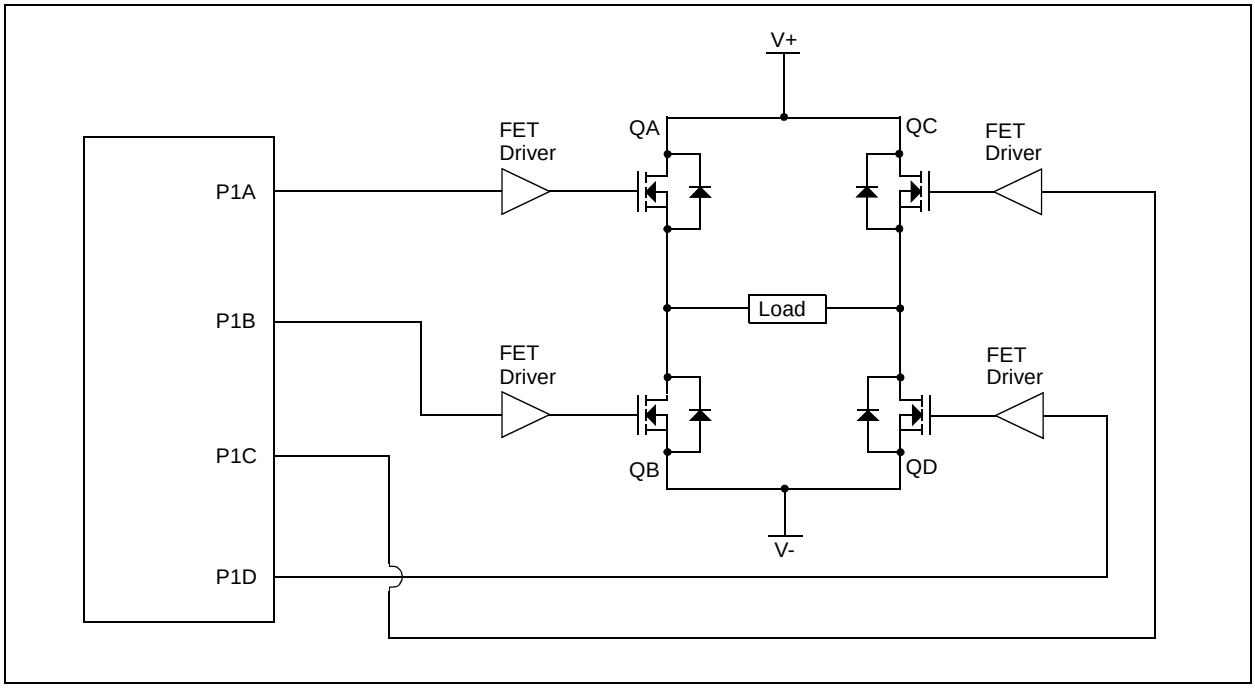
In Full-Bridge mode, all four pins are used as outputs. An example of full-bridge application is shown in Figure 11-10.

In the Forward mode, pin CCP1/P1A is driven to its active state, pin P1D is modulated, while P1B and P1C will be driven to their inactive state as shown in Figure 11-11.

In the Reverse mode, P1C is driven to its active state, pin P1B is modulated, while P1A and P1D will be driven to their inactive state as shown Figure 11-11.

P1A, P1B, P1C and P1D outputs are multiplexed with the PORT data latches. The associated TRIS bits must be cleared to configure the P1A, P1B, P1C and P1D pins as outputs.

FIGURE 11-10: EXAMPLE OF FULL-BRIDGE APPLICATION



11.4.4 ENHANCED PWM AUTO-SHUTDOWN MODE

The PWM mode supports an Auto-Shutdown mode that will disable the PWM outputs when an external shutdown event occurs. Auto-Shutdown mode places the PWM output pins into a predetermined state. This mode is used to help prevent the PWM from damaging the application.

The auto-shutdown sources are selected using the ECCPASx bits of the ECCPAS register. A shutdown event may be generated by:

- A logic '0' on the INT pin
- Comparator 1
- Comparator 2
- Setting the ECCPASE bit in firmware

A shutdown condition is indicated by the ECCPASE (Auto-Shutdown Event Status) bit of the ECCPAS register. If the bit is a '0', the PWM pins are operating normally. If the bit is a '1', the PWM outputs are in the shutdown state.

When a shutdown event occurs, two things happen:

The ECCPASE bit is set to '1'. The ECCPASE will remain set until cleared in firmware or an auto-restart occurs (see **Section 11.4.5 "Auto-Restart Mode"**).

The enabled PWM pins are asynchronously placed in their shutdown states. The PWM output pins are grouped into pairs [P1A/P1C] and [P1B/P1D]. The state of each pin pair is determined by the PSSAC and PSSBD bits of the ECCPAS register. Each pin pair may be placed into one of three states:

- Drive logic '1'
- Drive logic '0'
- Tri-state (high-impedance)

REGISTER 11-2: ECCPAS: ENHANCED CAPTURE/COMPARE/PWM AUTO-SHUTDOWN CONTROL REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ECCPASE	ECCPAS2	ECCPAS1	ECCPAS0	PSSAC1	PSSAC0	PSSBD1	PSSBD0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ECCPASE:** ECCP Auto-Shutdown Event Status bit
1 = A shutdown event has occurred; ECCP outputs are in shutdown state
0 = ECCP outputs are operating

bit 6-4 **ECCPAS<2:0>:** ECCP Auto-shutdown Source Select bits
000 = Auto-Shutdown is disabled
001 = Comparator 1 output change
010 = Comparator 2 output change
011 = Either Comparator 1 or 2 change
100 = VIL on INT pin
101 = VIL on INT pin or Comparator 1 change
110 = VIL on INT pin or Comparator 2 change
111 = VIL on INT pin or Comparator 1 or 2 change

bit 3-2 **PSSACn:** Pins P1A and P1C Shutdown State Control bits
00 = Drive pins P1A and P1C to '0'
01 = Drive pins P1A and P1C to '1'
1x = Pins P1A and P1C tri-state

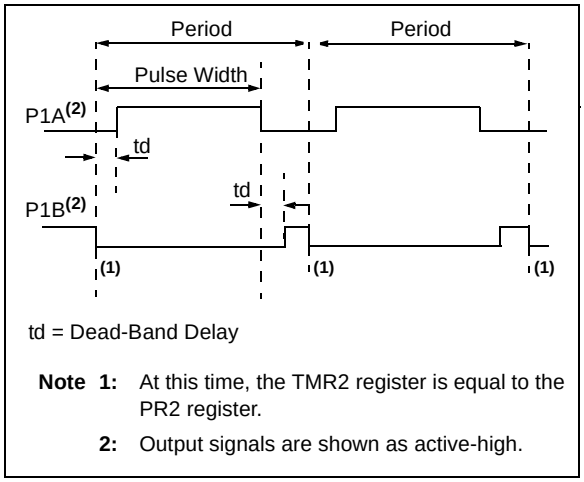
bit 1-0 **PSSBDn:** Pins P1B and P1D Shutdown State Control bits
00 = Drive pins P1B and P1D to '0'
01 = Drive pins P1B and P1D to '1'
1x = Pins P1B and P1D tri-state

11.4.6 PROGRAMMABLE DEAD-BAND DELAY MODE

In half-bridge applications where all power switches are modulated at the PWM frequency, the power switches normally require more time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches may be on for a short period of time until one switch completely turns off. During this brief interval, a very high current (*shoot-through current*) will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on either of the power switches is normally delayed to allow the other switch to completely turn off.

In Half-Bridge mode, a digitally programmable dead-band delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See **Section FIGURE 11-17: "Example of Half-Bridge Applications"** for illustration. The lower seven bits of the associated PWM1CON register (Register 11-3) sets the delay period in terms of microcontroller instruction cycles (TCY or 4 TOSC).

FIGURE 11-16: EXAMPLE OF HALF-BRIDGE PWM OUTPUT



td = Dead-Band Delay

Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signals are shown as active-high.

FIGURE 11-17: EXAMPLE OF HALF-BRIDGE APPLICATIONS

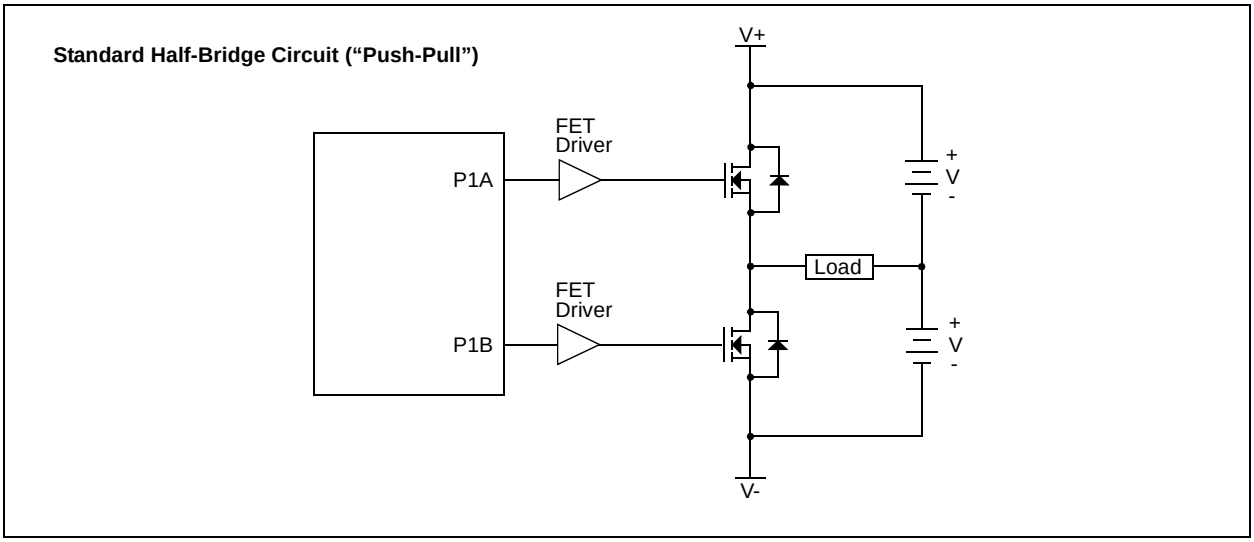
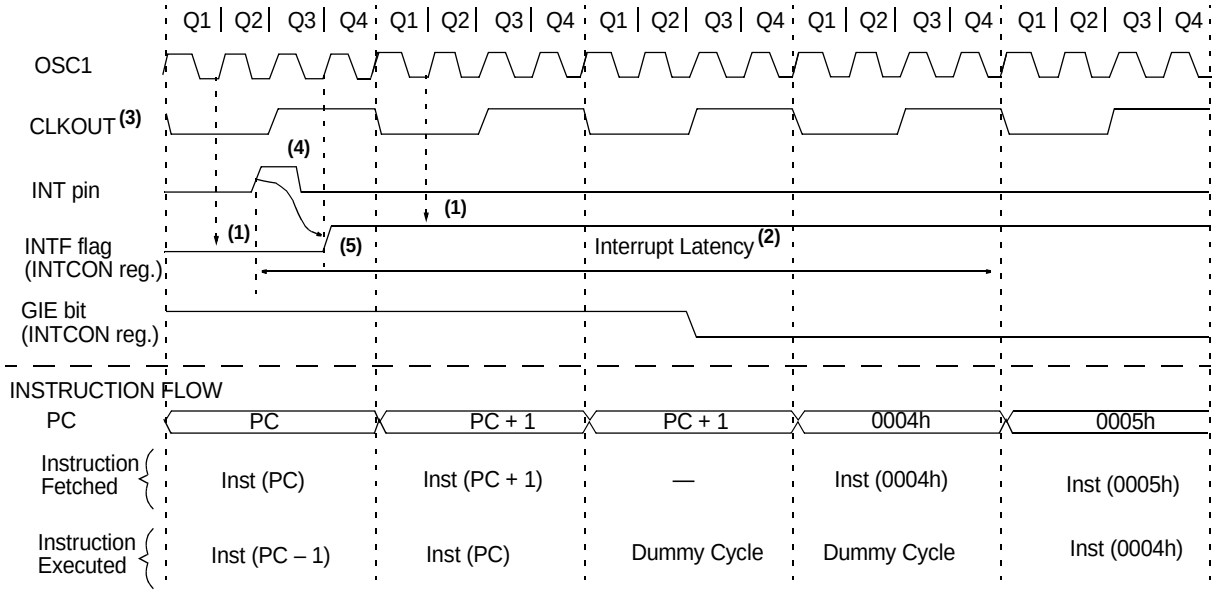


FIGURE 12-8: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-4 TCY. Synchronous latency = 3 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in INTOSC and RC Oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 15.0 "Electrical Specifications"**.

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

TABLE 12-6: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 0000
IOCA	—	—	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0	--00 0000	--00 0000
PIR1	EEIF	ADIF	CCP1IF	C2IF	C1IF	OSFIF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	EEIE	ADIE	CCP1IE	C2IE	C1IE	OSFIE	TMR2IE	TMR1IE	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, – = unimplemented read as '0', q = value depends upon condition. Shaded cells are not used by the interrupt module.

13.0 INSTRUCTION SET SUMMARY

The PIC16F684 instruction set is highly orthogonal and is comprised of three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

Each PIC16 instruction is a 14-bit word divided into an **opcode,** which specifies the instruction type and one or more **operands,** which further specify the operation of the instruction. The formats for each of the categories is presented in Figure 13-1, while the various opcode fields are summarized in Table 13-1.

Table 13-2 lists the instructions recognized by the MPASM™ assembler.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator, which selects the bit affected by the operation, while 'f' represents the address of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8-bit or 11-bit constant, or literal value.

One instruction cycle consists of four oscillator periods; for an oscillator frequency of 4 MHz, this gives a nominal instruction execution time of 1 µs. All instructions are executed within a single instruction cycle, unless a conditional test is true, or the program counter is changed as a result of an instruction. When this occurs, the execution takes two instruction cycles, with the second cycle executed as a NOP.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

13.1 Read-Modify-Write Operations

Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (R-M-W) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register.

For example, a CLRF PORTA instruction will read PORTA, clear all the data bits, then write the result back to PORTA. This example would have the unintended consequence of clearing the condition that set the RAIF flag.

TABLE 13-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1.
PC	Program Counter
$\overline{TO}$	Time-out bit
C	Carry bit
DC	Digit carry bit
Z	Zero bit
$\overline{PD}$	Power-down bit

FIGURE 13-1: GENERAL FORMAT FOR INSTRUCTIONS

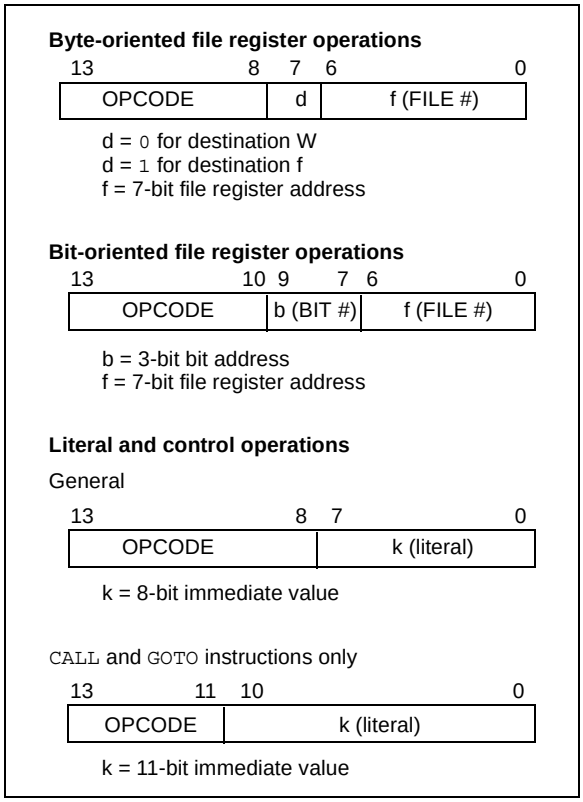


TABLE 13-2: PIC16F684 INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb	LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS							
ADDWF	f, d	Add W and f	1	00 0111 dfff ffff		C, DC, Z	**1, 2**
ANDWF	f, d	AND W with f	1	00 0101 dfff ffff		Z	**1, 2**
CLRF	f	Clear f	1	00 0001 lfff ffff		Z	**2**
CLRW	–	Clear W	1	00 0001 0xxx xxxx		Z	
COMF	f, d	Complement f	1	00 1001 dfff ffff		Z	**1, 2**
DECF	f, d	Decrement f	1	00 0011 dfff ffff		Z	**1, 2**
DECFSZ	f, d	Decrement f, Skip if 0	1**(2)**	00 1011 dfff ffff			**1, 2, 3**
INCF	f, d	Increment f	1	00 1010 dfff ffff		Z	**1, 2**
INCFSZ	f, d	Increment f, Skip if 0	1**(2)**	00 1111 dfff ffff			**1, 2, 3**
IORWF	f, d	Inclusive OR W with f	1	00 0100 dfff ffff		Z	**1, 2**
MOVF	f, d	Move f	1	00 1000 dfff ffff		Z	**1, 2**
MOVWF	f	Move W to f	1	00 0000 lfff ffff			
NOP	–	No Operation	1	00 0000 0xx0 0000			
RLF	f, d	Rotate Left f through Carry	1	00 1101 dfff ffff		C	**1, 2**
RRF	f, d	Rotate Right f through Carry	1	00 1100 dfff ffff		C	**1, 2**
SUBWF	f, d	Subtract W from f	1	00 0010 dfff ffff		C, DC, Z	**1, 2**
SWAPF	f, d	Swap nibbles in f	1	00 1110 dfff ffff			**1, 2**
XORWF	f, d	Exclusive OR W with f	1	00 0110 dfff ffff		Z	**1, 2**
BIT-ORIENTED FILE REGISTER OPERATIONS							
BCF	f, b	Bit Clear f	1	01 00bb bfff ffff			**1, 2**
BSF	f, b	Bit Set f	1	01 01bb bfff ffff			**1, 2**
BTFSC	f, b	Bit Test f, Skip if Clear	1 **(2)**	01 10bb bfff ffff			**3**
BTFSS	f, b	Bit Test f, Skip if Set	1 **(2)**	01 11bb bfff ffff			**3**
LITERAL AND CONTROL OPERATIONS							
ADDLW	k	Add literal and W	1	11 111x kkkk kkkk		C, DC, Z	
ANDLW	k	AND literal with W	1	11 1001 kkkk kkkk		Z	
CALL	k	Call Subroutine	2	10 0kkk kkkk kkkk			
CLRWDT	–	Clear Watchdog Timer	1	00 0000 0110 0100		$\overline{TO}$, $\overline{PD}$	
GOTO	k	Go to address	2	10 1kkk kkkk kkkk			
IORLW	k	Inclusive OR literal with W	1	11 1000 kkkk kkkk		Z	
MOVLW	k	Move literal to W	1	11 00xx kkkk kkkk			
RETFIE	–	Return from interrupt	2	00 0000 0000 1001			
RETLW	k	Return with literal in W	2	11 01xx kkkk kkkk			
RETURN	–	Return from Subroutine	2	00 0000 0000 1000			
SLEEP	–	Go into Standby mode	1	00 0000 0110 0011		$\overline{TO}$, $\overline{PD}$	
SUBLW	k	Subtract W from literal	1	11 110x kkkk kkkk		C, DC, Z	
XORLW	k	Exclusive OR literal with W	1	11 1010 kkkk kkkk		Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF GPIO, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '`1`' for a pin configured as input and is driven low by an external device, the data will be written back with a '`0`'.

2: If this instruction is executed on the TMR0 register (and where applicable, d = `1`), the prescaler will be cleared if assigned to the Timer0 module.

3: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

15.4 DC Characteristics: PIC16F684-E (Extended)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D020E	**Power-down Base Current (IPD)(2)**	—	0.05	9	µA	2.0	WDT, BOR, Comparators, VREF and T1OSC disabled
		—	0.15	11	µA	3.0	
		—	0.35	15	µA	5.0	
D021E		—	1	17.5	µA	2.0	WDT Current(1)
		—	2	19	µA	3.0	
		—	3	22	µA	5.0	
D022E		—	42	65	µA	3.0	BOR Current(1)
		—	85	127	µA	5.0	
D023E		—	32	45	µA	2.0	Comparator Current(1), both comparators enabled
		—	60	78	µA	3.0	
		—	120	160	µA	5.0	
D024E		—	30	70	µA	2.0	CVREF Current(1) (high range)
		—	45	90	µA	3.0	
		—	75	120	µA	5.0	
D025E*		—	39	91	µA	2.0	CVREF Current(1) (low range)
		—	59	117	µA	3.0	
		—	98	156	µA	5.0	
D026E		—	4.5	25	µA	2.0	T1OSC Current(1), 32.768 kHz
		—	5	30	µA	3.0	
		—	6	40	µA	5.0	
D027E		—	0.30	12	µA	3.0	A/D Current(1), no conversion in progress
		—	0.36	16	µA	5.0	

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral ∆ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.

TABLE 15-9: PIC16F684 A/D CONVERTER (ADC) CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10 bits	bit	
AD02	EIL	Integral Error	—	—	±1	LSb	VREF = 5.12V
AD03	EDL	Differential Error	—	—	±1	LSb	No missing codes to 10 bits VREF = 5.12V
AD04	EOFF	Offset Error	—	—	±1	LSb	VREF = 5.12V
AD07	EGN	Gain Error	—	—	±1	LSb	VREF = 5.12V
AD06 AD06A	VREF	Reference Voltage(3)	2.2 2.7	—	— VDD	V	 Absolute minimum to ensure 1 LSb accuracy
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	
AD09*	IREF	VREF Input Current(3)	10	—	1000	µA	During VAIN acquisition. Based on differential of VHOLD to VAIN.
			—	—	50	µA	During A/D conversion cycle.

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC VREF is from external VREF or VDD pin, whichever is selected as reference input.

4: When ADC is off, it will not consume any current other than leakage current. The power-down current specification includes any such leakage from the ADC module.

FIGURE 16-16: BOR IPD vs. VDD OVER TEMPERATURE

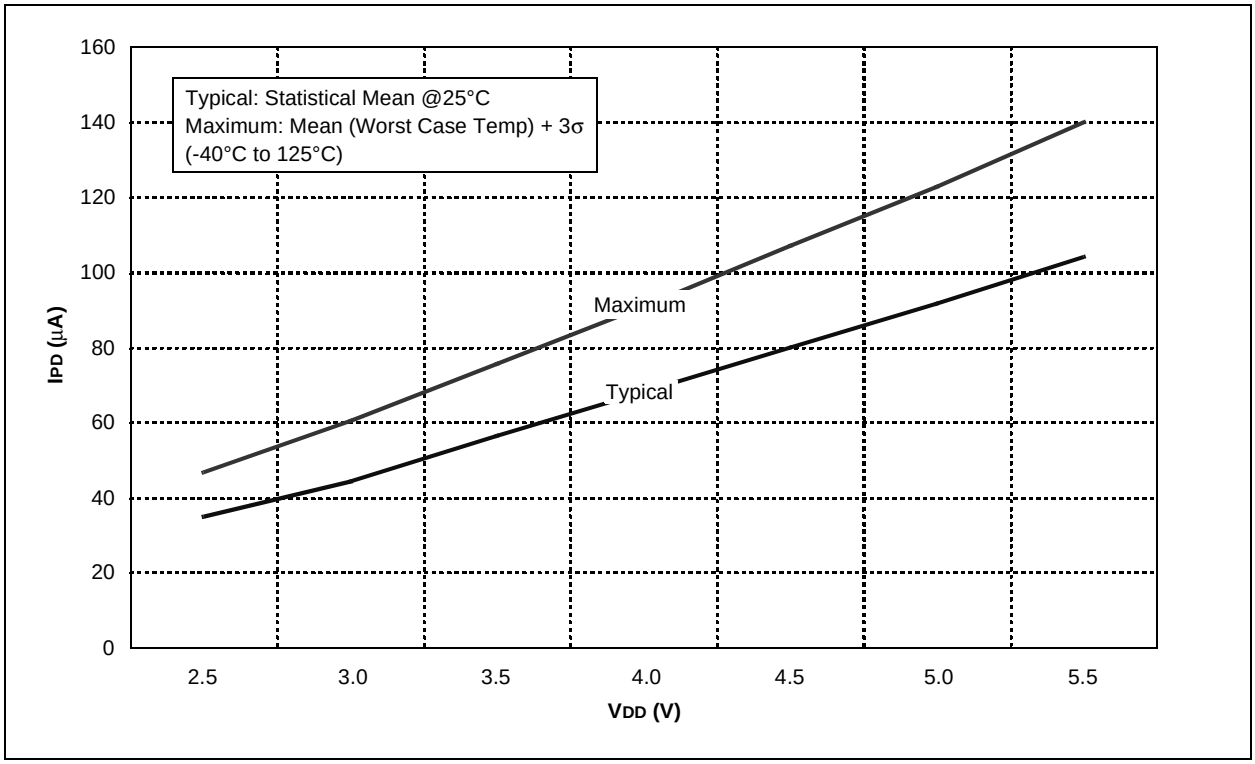


FIGURE 16-17: TYPICAL WDT IPD vs. VDD OVER TEMPERATURE

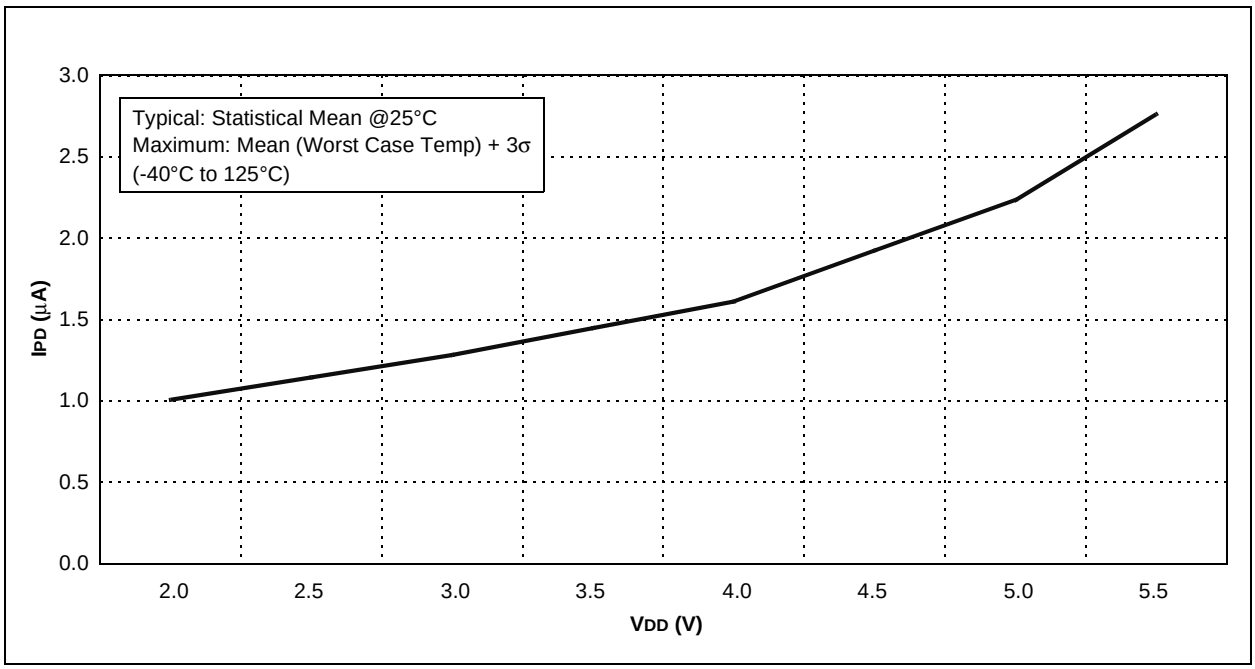


FIGURE 16-32: LFINTOSC FREQUENCY vs. VDD OVER TEMPERATURE (31 kHz)

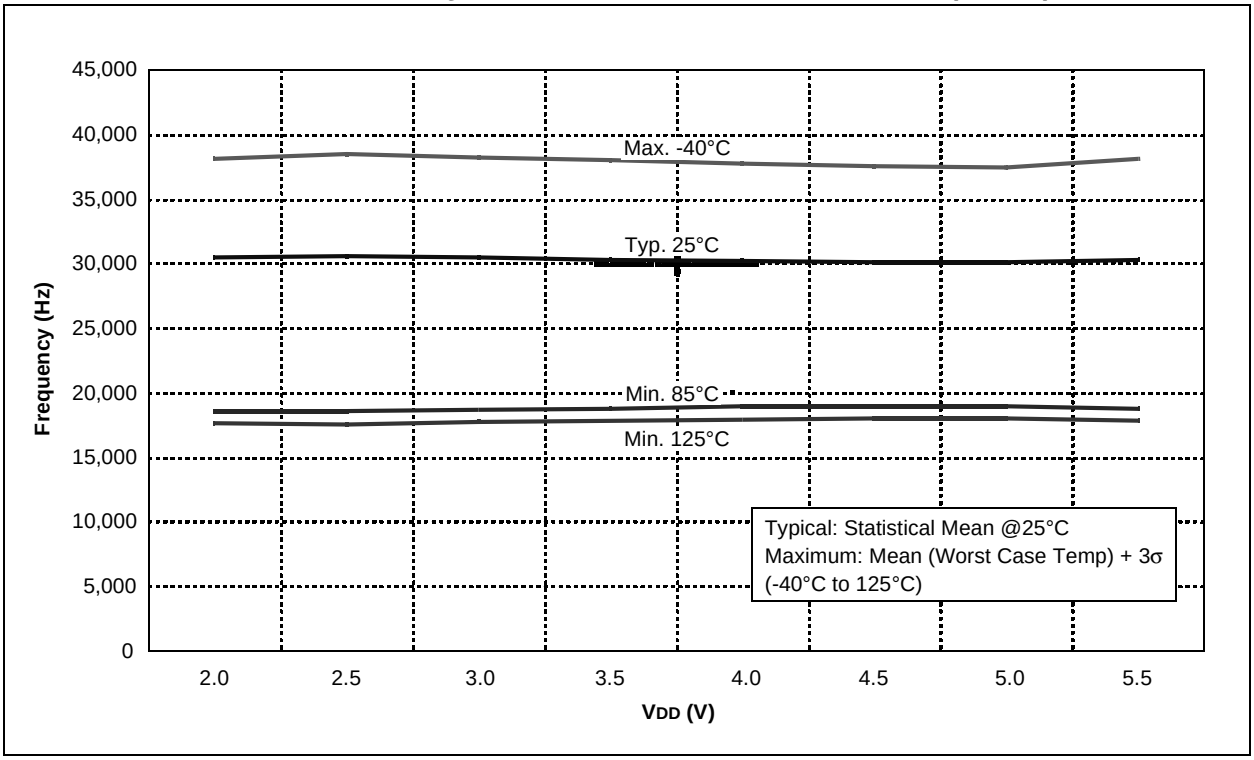
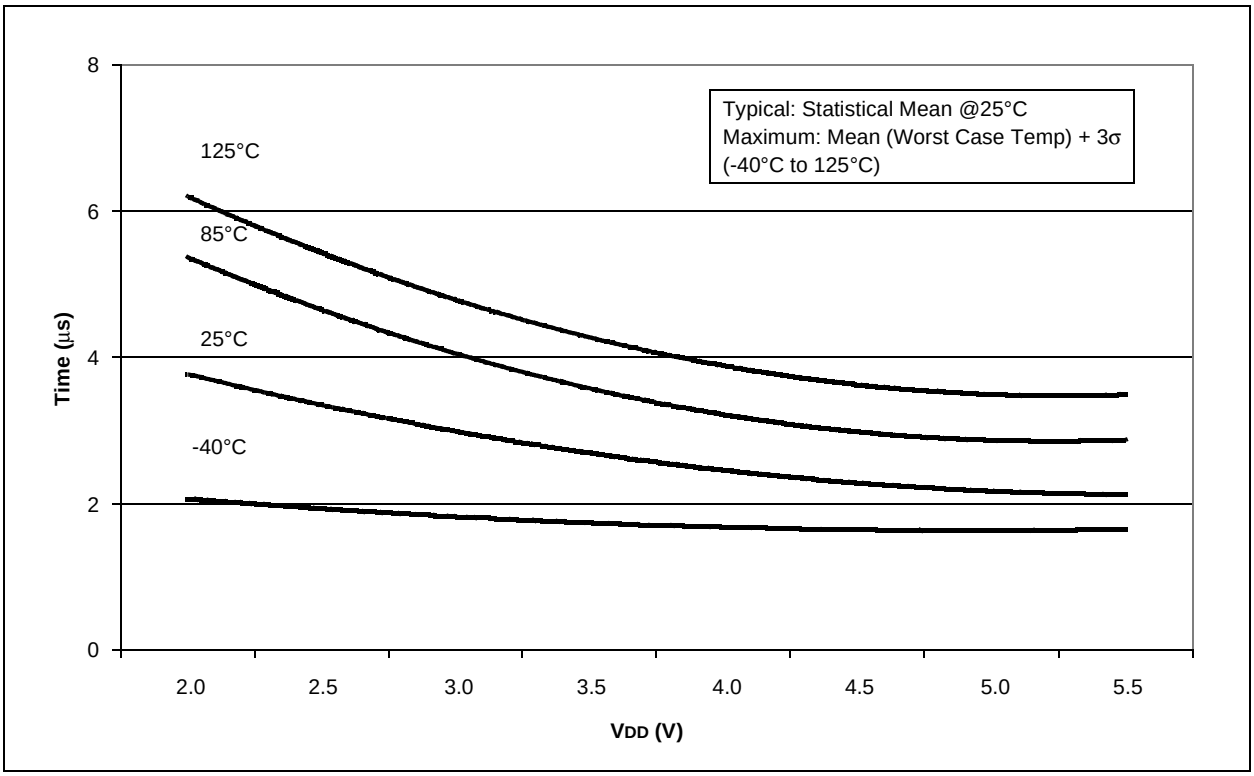


FIGURE 16-33: ADC CLOCK PERIOD vs. VDD OVER TEMPERATURE



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